© Copy	tial Composition right 2005. IPC, Bani ional and Pan-Americ	nockburn, Illinois. A	ll rights reserved ations.	under both	This docume level parts, th	ent is a declaration he declaration en	on of the su	bstances w all lower	vithin the manufactu level materials for w	rer listed ite which the ma	m. Note: i nufacture	if the item is an as r has engineering	sembly with low responsibility.	
				Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
upplier Information														
Company name*	Company uni	Company unique ID			Unique ID Authority				Response	Response Date*				
nsemi									2023-06-08					
Contact Name	Title - Contac	Title - Contact			Phone - Contact*				Email - Contact*					
Product-Env-Stewards	Product Envir	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
uthorized Representative*	Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Product Envir	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Nur	Requester Item Number Mfr Iter		m Number Mfr Item Name			Effective Date	Date Version Manufacturing Site		W	eight*	UOM	Unit Type		
		AP0101AT2L00XPG 1 MP C A0-DR		MP Co-Processor		2023-06-08		М	MY5		5.34	mg	Each	
Ianufacturing Proccess	s Information													
Terminal Plating / Grid Array Material Ter		Terminal Base A	erminal Base Alloy J-STD-020 MSI		Rating	Peak Proce	ak Process Body Temperature		Max Time at Peak	Temperatu	re Numl	ber of Reflow Cyc	les	
SnAgCu		CU Alloy	CU Alloy 3			260		C 30		seconds 3				
omments														
TTENTION: MSL 3 Rated i	tem requires Bake a	nd Dry Pack (after	electrical test)											
or more information regardi	ng material composi	ition please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.95	mg		Misc.	proprietary data		0.0086	mg
			Supplier	Silicon (Si)	7440-21-3		2.9385	mg
			Supplier	Aluminum (Al)	7429-90-5		0.003	mg
Die Attach Epoxy	0.26	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0026	mg
			Supplier	Filler (SiO2)	68909-20-6		0.104	mg
			Supplier	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0		0.0026	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0468	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.104	mg
Mold Compound-Black	33.58	mg		Epoxy resin	proprietary data		1.5111	mg
			Supplier	Phenolic Resin	Proprietary Data		1.5111	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1007	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30.4571	mg
Solder Ball	10.5	mg	Supplier	Silver (Ag)	7440-22-4		0.315	mg
			Supplier	Tin (Sn)	7440-31-5		10.1325	mg
			Supplier	Copper (Cu)	7440-50-8		0.0525	mg
Substrate and Solder Mask	1.06	mg	Supplier	Talc	14807-96-6		0.0382	mg
			Supplier	Epoxy Resin	26875-67-2		0.653	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0106	mg
			Supplier	Misc.	Proprietary Data		0.0286	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.3297	mg
Substrate Copper Foil	1.59	mg	Supplier	Copper (Cu)	7440-50-8		1.59	mg
Substrate - Core Material	8.54	mg		Epoxy resin	proprietary data		1.8506	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		6.6894	mg
Substrate Plating-Au	0.37	mg	Supplier	Gold (Au)	7440-57-5		0.37	mg
Substrate Plating-Cu	3.83	mg	Supplier	Copper (Cu)	7440-50-8		3.83	mg
Substrate Plating-Ni	1.3	mg	В	Nickel (Ni)	7440-02-0		1.3	mg
Wire Bond - Au	1.36	mg	Supplier	Gold (Au)	7440-57-5		1.36	mg